



## UNITED STATES PATENT AND TRADEMARK OFFICE

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CONFIRMATION NO. 1301

Bib Data Sheet

SERIAL NUMBER 09/945,241	FILING DATE 08/31/2001 RULE	CLASS 257	GROUP ART UNIT 2815	ATTORNEY DOCKET NO. 9319I-000277
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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

*none*

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

JAPAN 2000-267076 09/04/2000 *1m*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 10/04/2001

Foreign Priority claimed	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no		
35 USC 119 (a-d) conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance		
Verified and Acknowledged	<i>1m</i> Examiner's Signature Initials		
STATE OR COUNTRY	SHEETS DRAWING	TOTAL CLAIMS	INDEPENDENT CLAIMS
JAPAN	13	29	4

## ADDRESS

27572

## TITLE

Method for forming a bump, semiconductor device and method of fabricating same, semiconductor chip, circuit board, and electronic instrument

FILING FEE RECEIVED 1116	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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